

Title (en)
SEMICONDUCTOR PACKAGE AND ITS MANUFACTURING METHOD

Title (de)
HALBLEITERKAPSELUNG UND VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)
BOÎTIER SEMI-CONDUCTEUR ET SON PROCÉDÉ DE FABRICATION

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Application
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Priority
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Abstract (en)
A semiconductor package includes at least: a workpiece at least one surface of which is equipped with a device; a wall portion provided along an outer circumference of the device and is spaced apart from the device; and a cover member that is arranged above the device so as to form a first space and is supported by the workpiece via the wall portion, in which the first space includes at least one second space that communicates with an external space.

IPC 8 full level
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